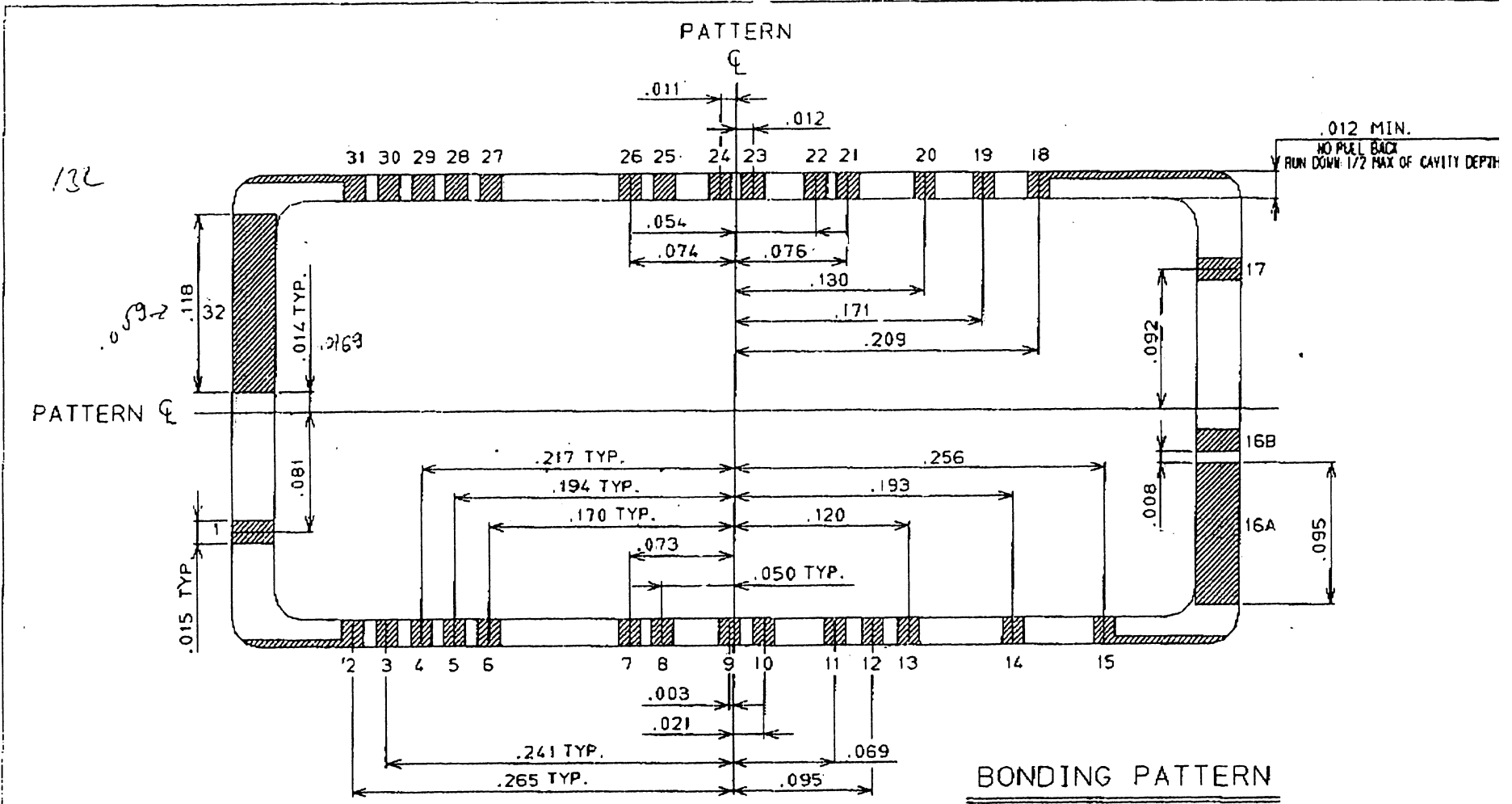


NOTES

- PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
- SEAL AREA TO BE METALLIZED.
- DIE ATTACH AREA TO BE METALLIZED.
- SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
- B/F NO.16A,16B TO BE ELECTRICALLY CONNECTED TO PIN NO.16.
- LEAD RESISTANCE : 1.00Ω MAX.

MULTIPLICATION	NAME 32 LEAD SIDE BRAZED PACKAGE				TOLERANCE ± .005 UNLESS OTHERWISE SPECIFIED		SB032ADB42-1 S-0 D-0				
	SCALE 4/1				MATERIAL AS INDICATED		DRAWN K.I	CHECKED H.S/S.F	APPROVED T.A	DATE DEC.1.'95	
	CHANGED				DATE	DRAWN	CHECKED	APPROVED	DRAWING NO. KD-S95B42		
					KYOCERA		KYOCERA CORPORATION KYOTO JAPAN			SHEET 1/	



MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						32 LEAD SIDE BRAZED PACKAGE	(UNLESS OTHERWISE SPECIFIED)	K. I	H.S/S.F	T. A	DEC. 1 '85
						SCALE 15 / 1	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		BREV 2/	
								KD-595B42			

CSB03218